What is claimed is:

1. An integrated bevel cleaning [IBU] apparatus,

5 comprising:

a transfer position where a substrate is positioned for processing and where a substrate is positioned after processing;

a rinse position where the substrate is rinsed; and

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an each position where the substrate edge bead is removed; and

an actuator for positioning the substrate in the transfer position, the rinse position and the etch position.

2. The 150 apparatus of claim 1 further comprising a substrate centering hoop for supporting the substrate in the transfer position.

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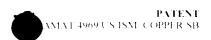
- 3. The IBC apparatus of claim 2 further comprising a substrate centering hoop rinsing nozzle.
- The TBC of claim 1 function comprising at least one
 rinsing nozzle located proximate said rinsing position for rinsing at least an edge region of the substrate.
- 5. The IBC of claim 4 wherein said at least one rinsing noticle is a plurality of noticles positioned to rinse both situations in the substruct.
 - 6. The IBC of claim 1 wherein said transfer position is accessible by at least one slit valve.



- T. The IBC apparatus of claim 1 wherein said actuator comprises a spindle assembly for retaining a substrate and rotating the substrate, and a linear actuator for raising 5 and lowering said spindle assembly.
 - 8. The IEC apparatus of claim 7 wherein said spindle assembly comprises a vacuum chuck.
- 10 9. The IBC of claim 1 further comprising at least one etchant dispenser arm positioned proximate the etch position to apply etchant to the substrate.
- 11. The IBC apparatus of claim 9 wherein said etchant is applied to an edge exclusion zone of said substrate.
 - 11. The IBT apparators of claim 9 wherein said at least one etchant dispenser arm is rotatable into a position near the substrate and away form the substrate.

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- 12. The IBC apparatus of claim 11 wherein said at least one etchant dispenser arm is at least three etchant dispenser arms.
- 25 13. The IBC apparatus of claim 12 wherein said at least three etchant dispenser arms are coupled to a single motor for simultaneously rotating the at least three dispenser arms.
- 30 14. A method for etching electroplated material from a substrate within an integrated bevel cleaning (IBC) apparatus, comprising:



introducing the substrate into a transfer position within the IBC apparatus;

moving the substrate to a rinse position within the IBC apparatus;

finsing the substrate in the rinse position within the IBC apparatus;

moving the substructe to an etch position within the IBC apparatus; and

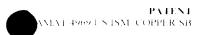
etching material from the substrate in the etch 10 position within the IBC apparatus.

- 15. The method of claim 14 wherein the substrate is rotated while in the rinse position and the etch position.
- 15 16. The method of claim 14 wherein the introducing step further comprises opening at least one of a plurality of slit valves.
- 17. The method of claim 14 wherein the step of etching 20 comprises positioning at least one etchant dispenser arm proximate the substrate.
- 18. The method of claim 17 wherein the at least one etchant dispenser arm comprises three etchant dispenser arms that are coupled to a single motor that imparts rotation in all three etchant dispenser arm simultaneously.
- 19. A system for processing substrates comprising:

 a loading station having at least one first chamber;

 30 a process region having at least one second chamber;

 an integrated bevel cleaning (IBC) apparatus
 comprising a transfer position through which a substrate



can be passed from said load station to said process region without processing being performed in said IBC apparatus.

- 20. The system of claim 19 wherein said at least one 5 second chamber is an electroplating chamber.
 - 21. The system of claim 19 wherein said load station comprises a first substrate handler and said second process region comprises a second substrate handler.

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22. The system of claim 19 wherein said IBC apparatus performs edge bead removal and substrate cleaning.